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Contract

## **UKRI-3154 Indium deposition system**

UK Research & Innovation

F03: Contract award notice

Notice identifier: 2024/S 000-000402

Procurement identifier (OCID): ocds-h6vhtk-040425

Published 5 January 2024, 4:06pm

### **Section I: Contracting authority**

#### **I.1) Name and addresses**

UK Research & Innovation

<https://www.ukri.org>, North Star Avenue, Harwell

Swindon

SN2 1FL

#### **Contact**

Declan Ward

#### **Email**

[commercial@ukri.org](mailto:commercial@ukri.org)

#### **Telephone**

+44 1793442000

#### **Country**

United Kingdom

**Region code**

UKK14 - Swindon

**Internet address(es)**

Main address

<https://www.ukri.org>

**I.4) Type of the contracting authority**

Body governed by public law

**I.5) Main activity**

Other activity

Research and innovation

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## **Section II: Object**

### **II.1) Scope of the procurement**

#### **II.1.1) Title**

UKRI-3154 Indium deposition system

Reference number

UKRI-3154

#### **II.1.2) Main CPV code**

- 14763000 - Indium

#### **II.1.3) Type of contract**

Supplies

#### **II.1.4) Short description**

STFC Interconnect provides a range of electronic and detector assembly techniques to scientific communities within STFC and our external collaborations. We have developed a process to perform surface preparation and make micro bumps of pure Indium metal, on a range of substrates including semiconductor wafers and semiconductor die. The resulting bumps are then used in our proprietary flip chip process to make many thousands or tens-of-thousands of electrical/mechanical connections in a single bonding step. The deposition process involves masking prior to deposition, then deposition, followed by removal of masked areas, leaving the desired bumps in place. Photo lithography (negative resist, lift-off) and shadow masking techniques are both used. We are now scaling this process into production and need new equipment capable of depositing on multiple substrates per day.

#### **II.1.6) Information about lots**

This contract is divided into lots: No

#### **II.1.7) Total value of the procurement (excluding VAT)**

Value excluding VAT: £185,067

### **II.2) Description**

#### **II.2.3) Place of performance**

NUTS codes

- UKJ14 - Oxfordshire

Main site or place of performance

Oxfordshire

#### **II.2.4) Description of the procurement**

STFC Interconnect provides a range of electronic and detector assembly techniques to scientific communities within STFC and our external collaborations. We have developed a process to perform surface preparation and make micro bumps of pure Indium metal, on a range of substrates including semiconductor wafers and semiconductor die. The resulting bumps are then used in our proprietary flip chip process to make many thousands or tens-of-thousands of electrical/mechanical connections in a single bonding step. The deposition process involves masking prior to deposition, then deposition, followed by removal of masked areas, leaving the desired bumps in place. Photo lithography (negative resist, lift-off) and shadow masking techniques are both used. We are now scaling this process into production and need new equipment capable of depositing on multiple substrates per day.

#### **II.2.5) Award criteria**

Quality criterion - Name: Quality / Weighting: 70

Cost criterion - Name: Price / Weighting: 30

#### **II.2.11) Information about options**

Options: No

#### **II.2.13) Information about European Union Funds**

The procurement is related to a project and/or programme financed by European Union funds: No

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## **Section IV. Procedure**

### **IV.1) Description**

#### **IV.1.1) Type of procedure**

Open procedure

#### **IV.1.8) Information about the Government Procurement Agreement (GPA)**

The procurement is covered by the Government Procurement Agreement: Yes

### **IV.2) Administrative information**

#### **IV.2.1) Previous publication concerning this procedure**

Notice number: [2023/S 000-028493](#)

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## **Section V. Award of contract**

### **Contract No**

UKRI-3154

### **Title**

Indium deposition system

A contract/lot is awarded: Yes

### **V.2) Award of contract**

#### **V.2.1) Date of conclusion of the contract**

20 December 2023

#### **V.2.2) Information about tenders**

Number of tenders received: 3

The contract has been awarded to a group of economic operators: No

#### **V.2.3) Name and address of the contractor**

HHV Ltd

Unit 14 Lloyds Court

Crawley

RH10 9QX

Country

United Kingdom

NUTS code

- UKJ14 - Oxfordshire

National registration number

06738557

The contractor is an SME

Yes

#### **V.2.4) Information on value of contract/lot (excluding VAT)**

Initial estimated total value of the contract/lot: £185,067

Total value of the contract/lot: £185,067

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## **Section VI. Complementary information**

### **VI.3) Additional information**

The contracting authority considers that this contract may be suitable for economic operators that are small or medium enterprises (SMEs). However, any selection of tenderers will be based solely on the criteria set out for the procurement. Procurement Contract Transparency Data: Redacted contract documents will be made available within the next 30 days on the UKRI website at: <https://www.ukri.org/about-us/procurement-contract-transparency-data/>

To view this notice, please click here:

<https://ukri.delta-esourcing.com/delta/viewNotice.html?noticeId=833356262>

GO Reference: GO-202415-PRO-24908448

#### **VI.4) Procedures for review**

##### **VI.4.1) Review body**

UK Research and Innovation

Polaris House,, North Star Avenue

Swindon

SN2 1FL

Email

[commercial@ukri.org](mailto:commercial@ukri.org)

Country

United Kingdom

##### **VI.4.2) Body responsible for mediation procedures**

UK Research and Innovation

Polaris House,, North Star Avenue

Swindon

SN2 1FL

Email

[commercial@ukri.org](mailto:commercial@ukri.org)

Country

United Kingdom